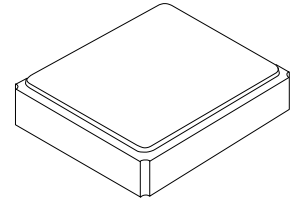


XTS4200

26.000000 MHz
TSX



SM2520-4

Features:

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitivity Level (MSL) : Level-1

Description and Applications:

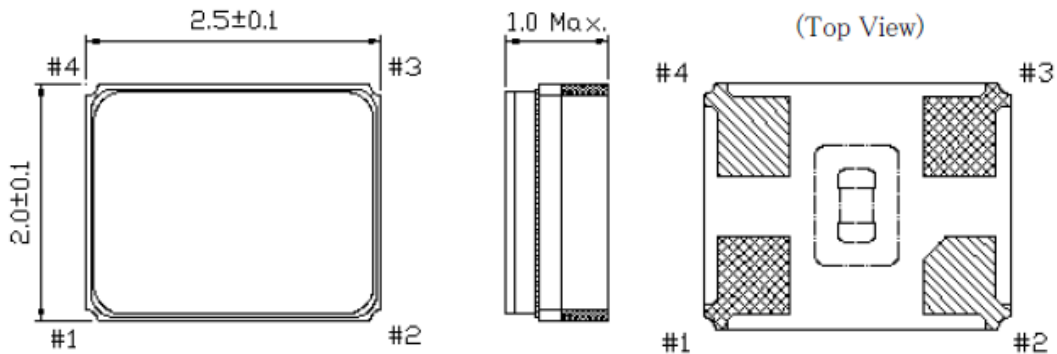
Surface mount 2.5mmx2.0mm crystal unit for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

Electrical Specifications:

XTS4200	Specification(Crystal)
Nominal Frequency	26.000000 MHz
Mode of Oscillation	Fundamental
Storage Temperature Range	-40°C to +125°C
Operating Temperature Range	-30°C to +105°C
Frequency Make Tolerance (FL)	+/-10 ppm @ 25°C +/- 3°C
¹ Frequency Stability over Operating Temperature Range	-12 to +/-10 ppm(-30°C to +85°C)
Equivalent Series Resistance (ESR)	50 Ω max
Nominal Drive Level	100 uW max
Load Capacitance (CL)	7 pF
Spurious modes resistance within +/- 500KHz	500 Ohm min
Tuning sensitivity (TS)	15+/-10% ppm/pF
Insulation Resistance at DC 100V	500 MΩ min
Quality Factor	75000 Min.
Full cycle temperature hysteresis	+/- 0.5 ppm (From -30°C to 85°C)
Small cycle temperature hysteresis	+/- 0.05 ppm (From -30°C to 85°C)

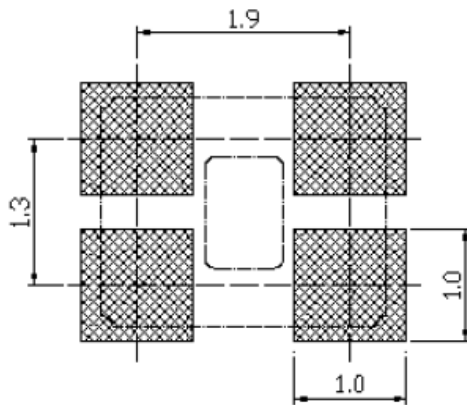
Full Cycle Frequency stability slope	+/- 0.05 ppm/°C (From -30°C to 85°C)
Small Cycle Frequency stability slope	+/- 0.05 ppm/°C (5°C small cycle)
Frequency Drift After Reflow	+/- 2.0 ppm after two reflow
Aging: First year After 2 year After 5 years After 10 years	+/- 0.7 ppm max +/- 1.4 ppm max +/- 2.5 ppm max +/- 5.0 ppm max
1st order coefficient (C1)	-0.40 to -0.10 ppm/°C
2nd order coefficient (C2)	+4.5 to +4.5 x10 ⁻⁴ ppm/°C ²
3rd order coefficient (C3)	+8.7 to +11.0 x10 ⁵ ppm/°C ³
Inflection point (Ti)	+29 to +32 °C
DLD spec: DLD2 DLDH2 FDLD FDLDH	0.01 uW to 100 uW 2.5 Ω max 1.5 Ω max 3.5 ppm max 0.7 ppm max
Resistance (25°C)	100K +/- 1% Ω
B-constant	4250 +/- 1% k (Evaluated from 25°C to 50°C, 1% tolerance)
Marking	Laser Marking

Mechanical Dimensions (unit: mm):

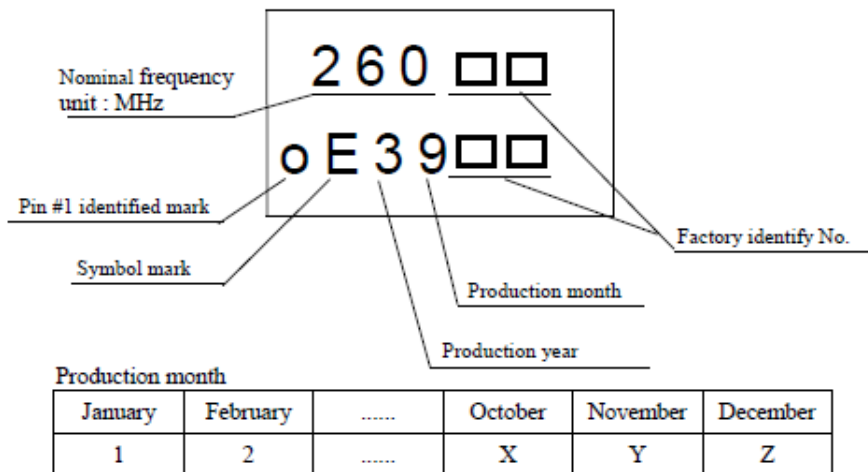


Pin	Connection
1	Xtal
2	GND, thermistor
3	Xtal
4	thermistor

Recommended Land Pattern: (unit: mm)



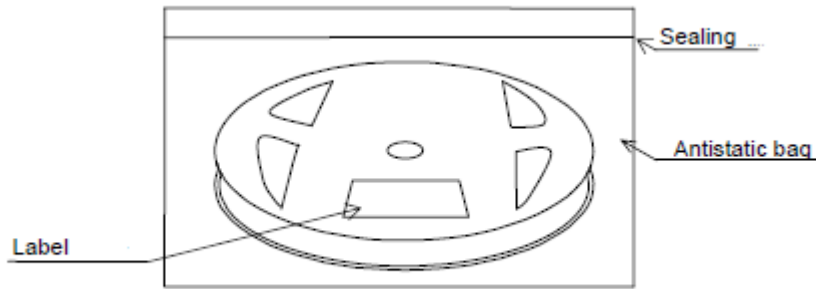
Marking:



- Nominal frequency is only one example.
- Nominal frequency omits the figure below the first place of decimals.
Ex)26.0 MHz..... [260]
- The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.

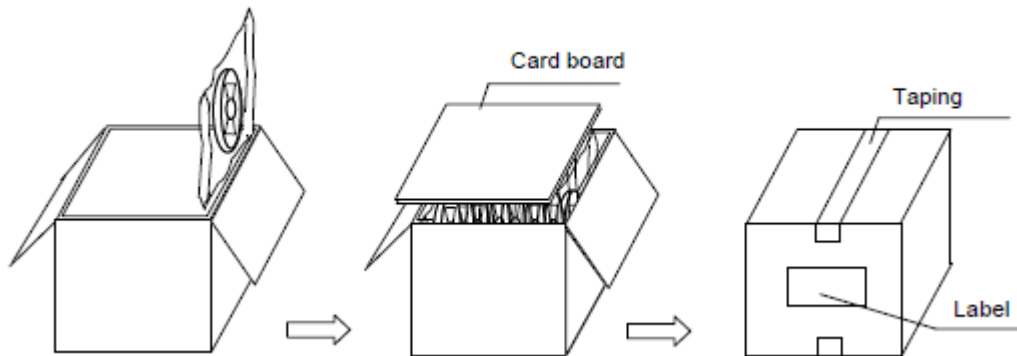
Packing Quantity/Packing:

3K pcs maximum per reel

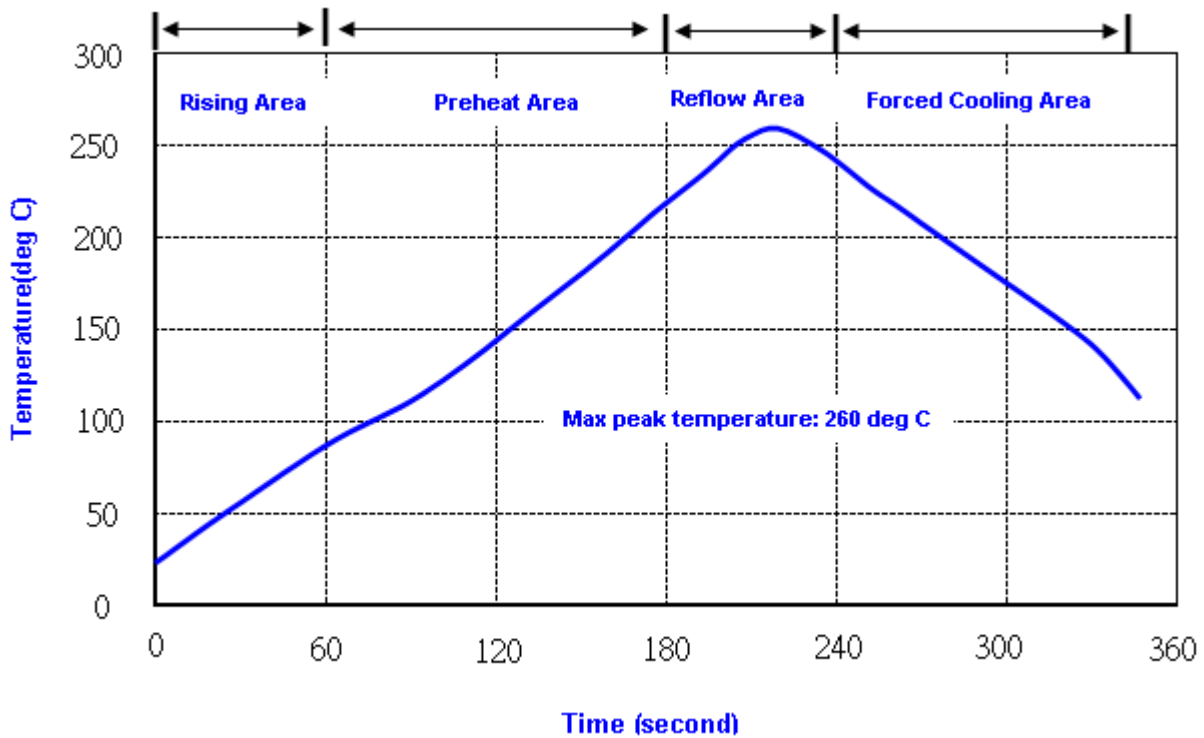


b) Packing to shipping carton

If there is space in the outer box, material is put in a shock absorbing together.



Reflow Profile:



- Note:** 1. Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec
2. Temperature: 217+/-5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard
Mechanical characteristics		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 260°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 55 Hz Sweep period : 1.0 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202F method 201A
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202F method 213C
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	MIL-STD 883G method 2003
Environmental characteristics		
Thermal Shock	Heat cycle conditions -55 °C (30min) ←→ 125 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.7
Humidity test	Temperature : 70 ± 2 °C Relative humidity : 90~95% Duration : 96 hours	MIL-STD 202F method 103B
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 883G method 1008.2 condition C
PCT test	Pressure: 2.06kg/cm ² (2.03*10 ⁵ pa) Temperature : 121 ± 2 °C Relative humidity : 100% Duration : 24 hours	EIAJED-4701-3 B-123A



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.